DS04-21340-2E

# ASSP Single Serial Input PLL Frequency Synthesizer **On-Chip 1.2 GHz Prescaler**

# **MB15E03**

### DESCRIPTION

The Fujitsu MB15E03 is serial input Phase Locked Loop (PLL) frequency synthesizer with a 1.2 GHz prescaler. A 64/65 or a 128/129 can be selected for the prescaler that enables pulse swallow operation.

The latest BiCMOS process technology is used, resultantly a supply current is limited as low as 3.5 mA typ. This operates with a supply voltage of 3.0 V (typ.).

Furthermore, a super charger circuit is included to get a fast tuning as well as low noise performance. As a result of this, MB15E03 is ideally suitable for digital mobile communications, such as GSM (Global System for Mobile Communications).

#### **■ FEATURES**

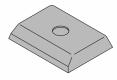
- High frequency operation: 1.2 GHz max
- Low power supply voltage: Vcc = 2.7 to 3.6 V
- Very Low power supply current : Icc = 3.5 mA typ. (Vcc = 3 V)
- Power saving function : I<sub>PS</sub> = 0.1 μA typ.
- Pulse swallow function: 64/65 or 128/129
- Serial input 14-bit programmable reference divider: R = 5 to 16,383
- Serial input 18-bit programmable divider consisting of:
  - Binary 7-bit swallow counter: 0 to 127
  - Binary 11-bit programmable counter: 5 to 2,047
- Wide operating temperature: Ta = -40 to 85°C
- Plastic 16-pin SSOP package (FPT-16P-M05) and 16-pin BCC package (LCC-16P-M02) WW.DZSC.CO

### ■ PACKAGES

16-pin, Plastic SSOP

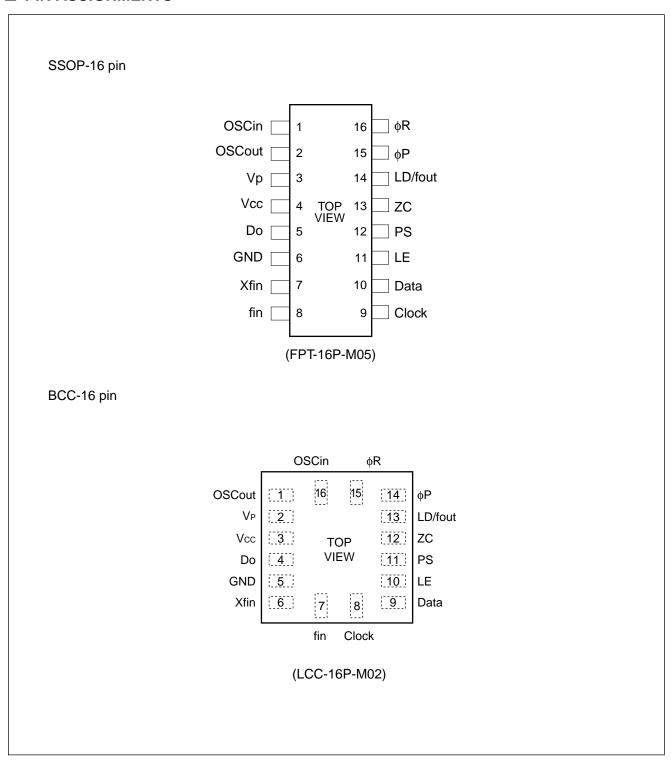
(FPT-16P-M05)

16-pin, Plastic BCC



(LCC-16P-M02)

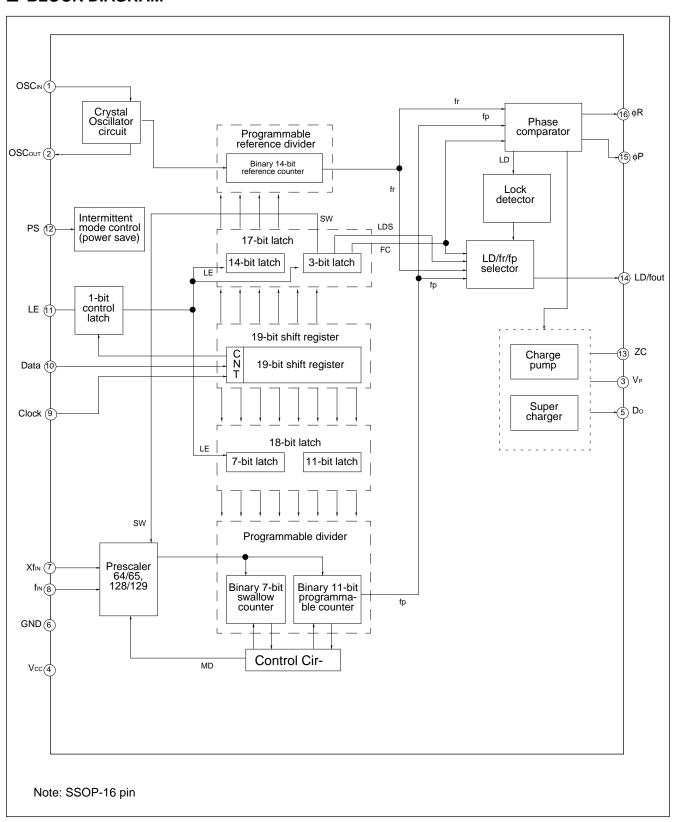
# **■ PIN ASSIGNMENTS**



# **■ PIN DESCRIPTIONS**

Pin	no.	Pin	1/0	Descriptions
SSOP	ВСС	name	I/O	Descriptions
1	16	OSCIN	I	Programmable reference divider input. Oscillator input. Connection for an crystal or a TCXO. TCXO should be connected with a coupling capacitor.
2	1	ОЅСоит	0	Oscillator output. Connection for an external crystal.
3	2	VP	-	Power supply voltage input for the charge pump.
4	3	Vcc	_	Power supply voltage input.
5	4	Do	0	Charge pump output. Phase of the charge pump can be reversed by FC bit.
6	5	GND	_	Ground.
7	6	Xfin	I	Prescaler complementary input, and should be grounded via a capacitor.
8	7	fin	I	Prescaler input. Connection with an external VCO should be done with AC coupling.
9	8	Clock	1	Clock input for the 19-bit shift register.  Data is shifted into the shift register on the rising edge of the clock.  (Open is prohibited.)
10	9	Data	ı	Serial data input using binary code. The last bit of the data is a control bit. (Open is prohibited.) Control bit = "H"; Data is transmitted to the programmable reference  counter. Control bit = "L"; Data is transmitted to the programmable counter.
11	10	LE	I	Load enable signal input (Open is prohibited.) When LE is high, the data in the shift register is transferred to a latch, according to the control bit in the serial data.
12	11	PS	ı	Power saving mode control. This pin must be set at "L" at Power-ON.  (Open is prohibited.) PS = "H"; Normal mode PS = "L"; Power saving mode
13	12	ZC	I	Forced high-impedance control for the charge pump (with internal pull up resistor.)  ZC = "H"; Normal Do output.  ZC = "L"; Do becomes high impedance.
14	13	LD/fout	0	Lock detect signal output(LD)/phase comparator monitoring output (fout).  The output signal is selected by LDS bit in the serial data.  LDS = "H"; outputs fout (fr/fp monitoring output)  LDS = "L"; outputs LD ("H" at locking, "L" at unlocking.)
15	14	φР	0	Phase comparator output for an external charge pump. Nch open drain output.
16	15	φR	0	Phase comparator output for an external charge pump. CMOS output.

# **■ BLOCK DIAGRAM**



### ■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Remark
Dower aupply voltage	Vcc	-0.5 to +4.0	V	
Power supply voltage	V <sub>P</sub> V <sub>CC</sub> to +6.0		V	
Input voltage	Vı	−0.5 to Vcc +0.5	V	
Output voltage	Vo	−0.5 to Vcc +0.5	V	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

### ■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol		Value	Unit	Remark		
Faranteter	Symbol	Min.	Тур.	Max.	Oille	Remark	
Power supply veltage	Vcc	2.7	3.0	3.6	V		
Power supply voltage	VP	Vcc	_	6.0	V		
Input voltage	Vı	GND	_	Vcc	V		
Operating temperature	Та	-40	_	+85	°C		

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always yse semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with repect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

# **■ ELECTRICAL CHARACTERISTICS**

 $(Vcc = 2.7 \text{ to } 3.6 \text{ V}, Ta = -40 \text{ to } +85^{\circ}\text{C})$ 

				(Vcc = 2.7	Value	10.		
Paramete	er	Symbol	Condition	Min.	Тур.	Max.	Unit	
Power supply current*1		Icc	fin = 1200 MHz, fosc = 12 MHz	_	3.5	_	mA	
Power saving current		Ips	PS = "L", ZC = "H" or open	_	0.1*2	10	μΑ	
Operating frequency		fin		100	_	1200	MHz	
Crystal oscillator opera	ating frequency	fosc	min. 500 mVp-p	3	_	40	MHz	
Input sensitivity	fin	Vfin	50 Ω system (Refer to the test circuit.)	-10	_	+2	dBm	
	OSCin	Vosc		500	_	Vcc	mVp-p	
Input voltage	Data, Clock,	Vін		Vcc × 0.7	_	_	V	
input voltage	LE, PS, ZC	VIL		_	_	$Vcc \times 0.3$	, v	
	Data, Clock,	Ін		-1.0	_	+1.0		
	LE, PS	IIL		-1.0	_	+1.0	μΑ	
Input current	ZC	Ін		-1.0	_	+1.0	<sub>     </sub>	
	20	Iı∟	Pull up input	-100	_	0	μA	
	OSCin	Іін		0	_	+100	μΑ	
	OSCIII	lıL		-100	_	0		
	φР	Vol	Open drain output	_	_	0.4	V	
	φR,	Vон	Vcc = 3 V, Iон = -1 mA	Vcc - 0.4	_	_	V	
Output voltage	LD/fout	Vol	Vcc = 3 V, IoL = 1 mA	_	_	0.4	, v	
	Do	V <sub>DOH</sub>	Vcc = 3 V, IDOH = -1 mA	Vp - 0.4	_	_	V	
	Do	VDOL	Vcc = 3 V, IDOL = 1 mA	_	_	0.4	\ \ \	
High impedance cutoff current	Do	loff	Vcc = 3 V, Vp = 6 V Voop = GND to 6 V	_	_	1.1	μΑ	
	φР	loL		1.0	_	_	mA	
	φR,	Іон		_	_	-1.0	mA	
	LD/fout	loL		1.0	_	_	IIIA	
Output current	Do	Ідон	Vcc = 3.0 V, Vp = 5 V, Vрон = 4.0 V Та = 25°С	-	-10.0	_	- mA	
	100	IDOL	Vcc = 3.0 V, Vp = 5 V, Vdol = 1.0 V Ta = 25°C	-	10.0	_	1 IIIA	

<sup>\*1:</sup> Conditions; Vcc = 3.0 V,  $Ta = 25^{\circ}C$ , in locking state.

<sup>\*2:</sup> Conditions; Vcc = 3.0 V,  $Ta = 25^{\circ}\text{C}$ , fosc = 12 MHz (-2 dB)

#### **■ FUNCTION DESCRIPTIONS**

#### **Pulse Swallow Function**

The divide ratio can be calculated using the following equation:

 $f_{VCO} = [(M \times N) + A] \times f_{OSC} \div R \quad (A < N)$ 

fvco : Output frequency of external voltage controlled oscillator (VCO) Ν : Preset divide ratio of binary 11-bit programmable counter (5 to 2,047)

Α : Preset divide ratio of binary 7-bit swallow counter ( $0 \le A \le 127$ )

: Output frequency of the reference frequency oscillator

: Preset divide ratio of binary 14-bit programmable reference counter (5 to 16,383)

: Preset divide ratio of modules prescaler (64 or 128)

### **Serial Data Input**

Serial data is processed using the Data, Clock, and LE pins. Serial data controls the programmable reference divider and the programmable divider separately.

Binary serial data is entered through the Data pin.

One bit of data is shifted into the shift register on the rising edge of the clock. When the load enable pin is high, stored data is latched according to the control bit data as follows:

Table.1 Control Bit

Control bit (CNT)	Destination of serial data
Н	17 bit latch (for the programmable reference divider)
L	18 bit latch (for the programmable divider)

### **Shift Register Configuration**

#### **Programmable Reference Counter** MS Data LS 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 C R R R R R R R R R R R R R R Ν 1 2 3 4 5 6 7 8 9 10 11 12 13 14 SW FC LDS Т

CNT: Control bit

[Table, 1] R1 to R14: Divide ratio setting bit for the programmable reference counter (5 to 16,383) [Table, 2]

SW : Divide ratio setting bit for the prescaler (64/65 or 128/129)

[Table, 5] : Phase control bit for the phase comparator [Table. 7] FC LDS: LD/fout signal select bit [Table, 6]

Note: Start data input with MSB first

#### **Programmable Reference Counter** MS Data LS 1 2 3 5 7 9 6 8 11 13 15 17 4 10 12 14 16 18 19 С Α Α Α Α Α Α Α Ν Ν Ν Ν Ν Ν Ν Ν Ν Ν Ν 2 5 7 5 Ν 3 4 6 1 2 3 4 6 7 8 9 10 11 Т CNT: Control bit [Table, 1] N1 to N11: Divide ratio setting bits for the programmable counter (5 to 2,047) [Table. 3] A1 to A7: Divide ratio setting bits for the swallow counter (0 to 127) [Table. 4] Note: Start data input with MSB first

Table2. Binary 14-bit Programmable Reference Counter Data Setting

Divide ratio (R)	R 14	R 13	R 12	R 11	R 10	R 9	R 8	R 7	R 6	R 5	R 4	R 3	R 2	R 1
5	0	0	0	0	0	0	0	0	0	0	0	1	0	1
6	0	0	0	0	0	0	0	0	0	0	0	1	1	0
		•		•	•	•			•	•		•	•	
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 5 is prohibited.

**Table.3 Binary 11-bit Programmable Counter Data Setting** 

Divide ratio (N)	N 11	N 10	N 9	N 8	N 7	<b>N</b> 6	N 5	N 4	N 3	N 2	N 1
5	0	0	0	0	0	0	0	0	1	0	1
6	0	0	0	0	0	0	0	0	1	1	0
	•	•	•			•	•	•	•	•	
2047	1	1	1	1	1	1	1	1	1	1	1

Note: • Divide ratio less than 5 is prohibited.

• Divide ratio (N) range = 5 to 2,047

**Table.4 Binary 7-bit Swallow Counter Data Setting** 

Divide ratio (A)	A 7	<b>A</b> 6	A 5	A 4	A 3	A 2	A 1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
	•						
127	1	1	1	1	1	1	1

Note: • Divide ratio (A) range = 0 to 127

**Table. 5 Prescaler Data Setting** 

SW	Prescaler Divide ratio
Н	64/65
L	128/129

Table. 6 LD/fout Output Select Data Setting

LDS	LD/fout output signal
Н	fout signal
L	LD signal

### Relation between the FC input and phase characteristics

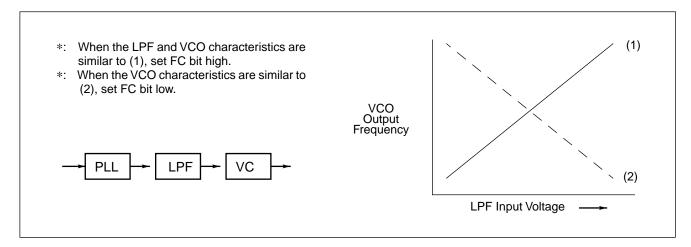
The FC bit changes the phase characteristics of the phase comparator. Both the internal charge pump output level (Do) and the phase comparator output ( $\phi R$ ,  $\phi P$ ) are reversed according to the FC bit. Also, the monitor pin (fout) output is controlled by the FC bit. The relationship between the FC bit and each of Do,  $\phi R$ , and  $\phi P$  is shown below.

Table. 7 FC Bit Data Setting (LDS = "H")

		FC =	High		FC = Low				
	Do	φR	φР	LD/fout	Do	φR	φР	LD/fout	
fr > fp	Н	L	L	(fr)	L	Н	Z*	(fp)	
fr < fp	L	Н	Z*	(fr)	Н	L	L	(fp)	
$f_r = f_p$	Z*	L	Z*	(fr)	Z*	L	Z*	(fp)	

<sup>\*:</sup> High impedance

When designing a synthesizer, the FC pin setting depends on the VCO and LPF characteristics.



### **Power Saving Mode (Intermittent Mode Control Circuit)**

Setting a PS pin to Low, the IC enters into power saving mode resultatly current sonsumption can be limited to 10µA (max.). Setting PS pin to High, power saving mode is released so that the IC works normally.

In addition, the intermittent operation control circuit is included which helps smooth start up from the power saving mode. In general, the power consumption can be saved by the intermittent operation that powering down or waking up the synthesizer. Such case, if the PLL is powered up uncontrolled, the resulting phase comparator output signal is unpredictable due to an undefined phase relation between reference frequency (f<sub>r</sub>) and comparison frequency (f<sub>p</sub>) and may in the worst case take longer time for lock up of the loop.

To prevent this, the intermittent operation control circuit enforces a limited error signal output of the phase detector during power up, thus keeping the loop locked.

During the power saving mode, the corresponding section except for indispensable circuit for the power saving function stops working, then current consumption is reduced to 10 µA (max.).

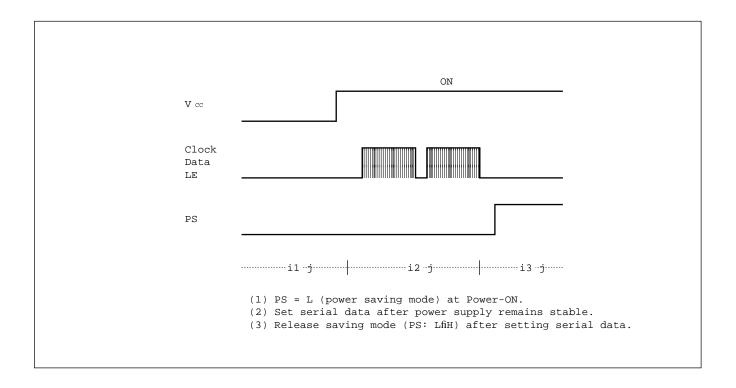
At that time, the Do and LD become the same state as when a loop is locking. That is, the Do becomes high impedance.

A VCO control voltage is naturally kept at the locking voltage which defined by a LPF's time constant. As a result of this, VCO's frequency is kept at the locking frequency.

- Note: While the power saving mode is executed, ZC pin should be set at "H" or open. If ZC is set at "L" during power saving mode, approximately 10 μA current flows.
  - PS pin must be set "L" at Power-ON.
  - The power saving mode can be released (PS: L  $\rightarrow$  H) 1 $\mu$ s later after power supply remains stable.
  - During the power saving mode, it is possible to input the serial data.

#### Table.8 PS Pin Setting

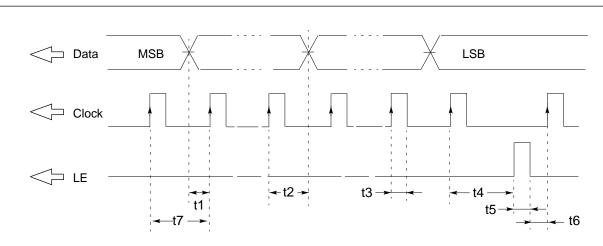
PS pin	Status
Н	Normal mode
L	Power saving mode



**Table.9 ZC Pin Setting** 

ZC pin	Do output		
Н	Normal output		
L	High impedance		

# ■ SERIAL DATA INPUT TIMING

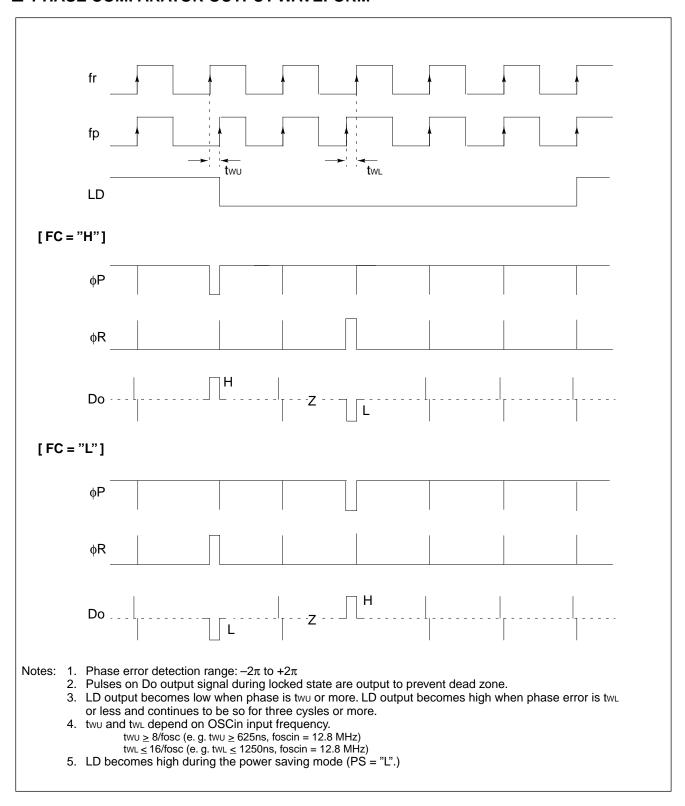


On rising edge of the clock, one bit of the data is transferred into the shift register.

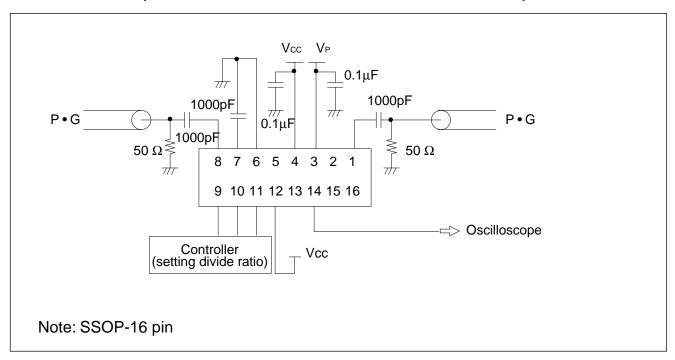
Parameter	Min.	Тур.	Max.	Unit
t1	20	_	_	ns
t2	20	_	_	ns
t3	30	_	_	ns
t4	30	_	_	ns

Parameter	Min.	Тур.	Max.	Unit
t5	100	_	ı	ns
t6	20	_	-	ns
t7	100	_	-	ns

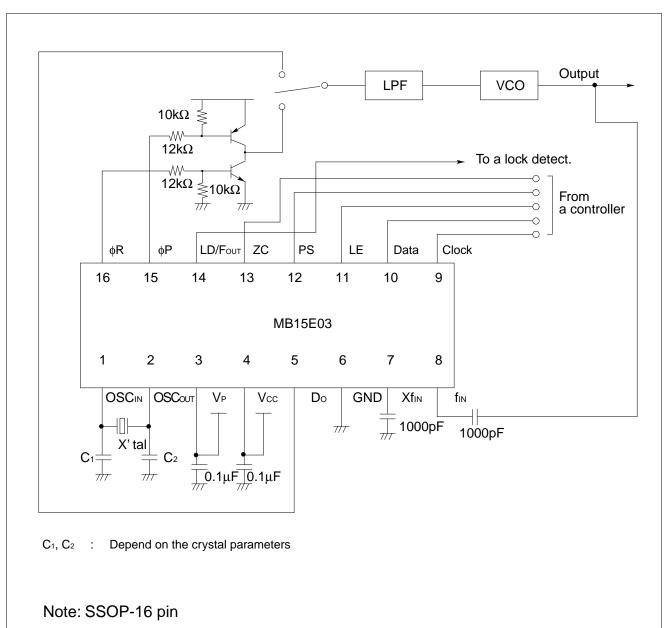
# **■ PHASE COMPARATOR OUTPUT WAVEFORM**



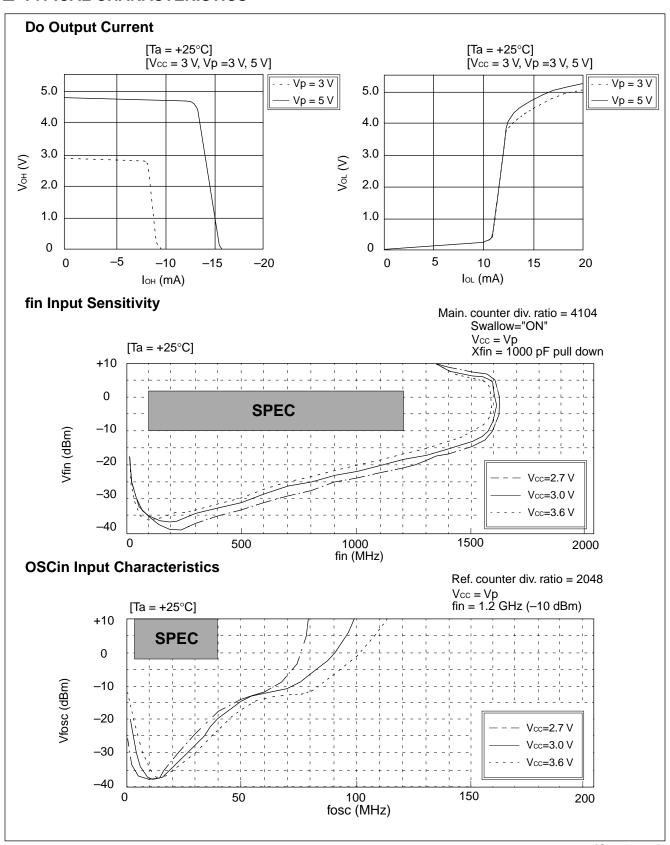
# ■ TEST CIRCUIT (FOR MEASURING INPUT SENSITIVITY FIN/OSCIN)



# **■ APPLICATION EXAMPLE**

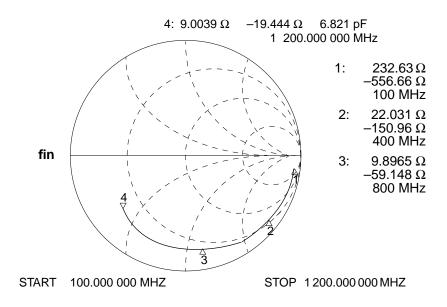


# **■ TYPICAL CHARACTERISTICS**

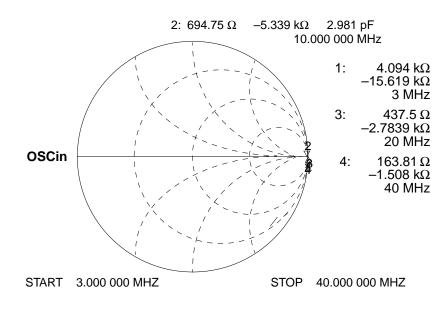


# (Continued)

# fin Input Impedance

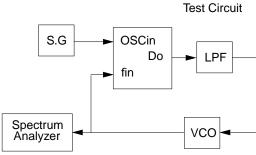


# **OSCin Input Impedance**

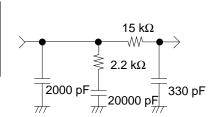


### **■ REFERENCE INFORMATION**

Typical plots measured with the test circuit are shown below. Each plot shows lock up time, phase noise and reference leakage.



- fvco = 1018 MHz
- Kv = 20 MHz/v
- fr = 200 kHz
- fosc = 13 MHz
- LPF:



# PLL Lock Up Time = 440 $\mu$ s

(1005.000 MHz  $\rightarrow$  1031.000 MHz, within  $\pm$  1kHz)

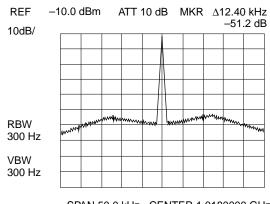
Δ MKr x : 439.89783 μs y : 25.94979 MHz 30.00300 MHz

1.000 kHz/div

29.99800 MHz

### **PLL Phase Noise**

@ within loop band = 76.2 dBc/Hz



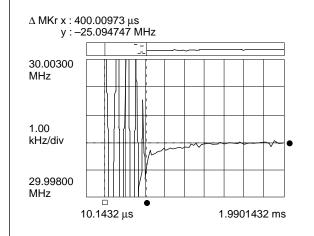
#### SPAN 50.0 kHz CENTER 1.0180000 GHz

### PLL Lock Up Time = 400 μs

 $10.2702 \, \mu s$ 

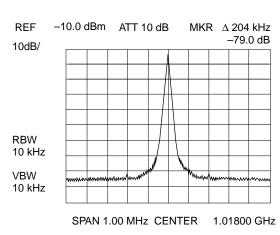
(1031.000 MHz  $\rightarrow$  1005.000 MHz, within  $\pm$  1kHz)

1.9902702 ms



### **PLL Reference Leakage**

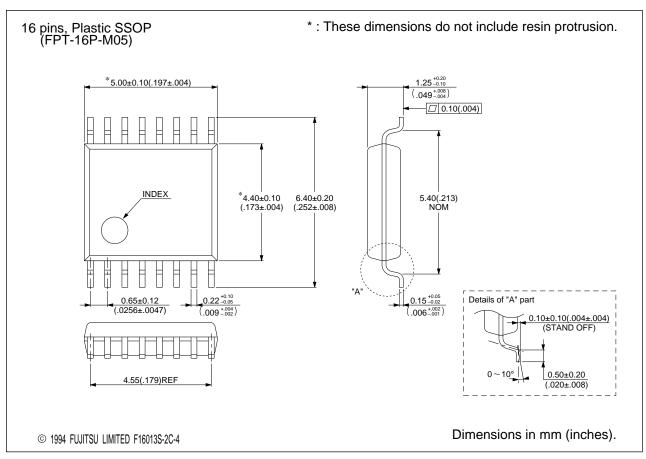
@ 200 kHz offset = 79.0 dBc



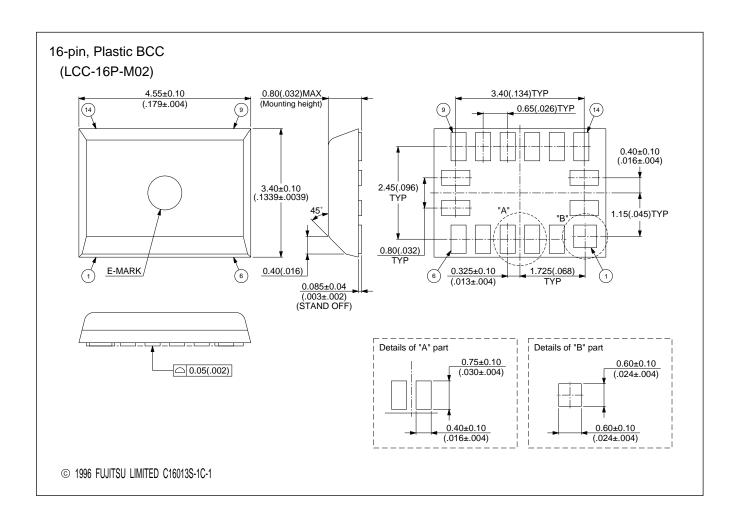
# **■** ORDERING INFORMATION

Part number	Package	Remarks
MB15E03 PFV1	16 pin, Plastic SSOP (FPT-16P-M05)	
MB15E03 PV	16 pin, Plastic BCC (LCC-16P-M02)	

# **■ PACKAGE DIMENSIONS**



(Continued)



# **FUJITSU LIMITED**

For further information please contact:

### Japan

FUJITSU LIMITED
Corporate Global Business Support Division
Electronic Devices
KAWASAKI PLANT, 4-1-1, Kamikodanaka
Nakahara-ku, Kawasaki-shi
Kanagawa 211-88, Japan

Tel: (044) 754-3763 Fax: (044) 754-3329

#### North and South America

FUJITSU MICROELECTRONICS, INC. Semiconductor Division 3545 North First Street San Jose, CA 95134-1804, U.S.A.

Tel: (408) 922-9000 Fax: (408) 432-9044/9045

#### **Europe**

FUJITSU MIKROELEKTRONIK GmbH Am Siebenstein 6-10 63303 Dreieich-Buchschlag Germany

Tel: (06103) 690-0 Fax: (06103) 690-122

### **Asia Pacific**

FUJITSU MICROELECTRONICS ASIA PTE. LIMITED #05-08, 151 Lorong Chuan New Tech Park Singapore 556741

Tel: (65) 281 0770 Fax: (65) 281 0220 All Rights Reserved.

The contents of this document are subject to change without notice. Customers are advised to consult with FUJITSU sales representatives before ordering.

The information and circuit diagrams in this document presented as examples of semiconductor device applications, and are not intended to be incorporated in devices for actual use. Also, FUJITSU is unable to assume responsibility for infringement of any patent rights or other rights of third parties arising from the use of this information or circuit diagrams.

FUJITSU semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION:

Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with FUJITSU sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

If any products described in this document represent goods or technologies subject to certain restrictions on export under the Foreign Exchange and Foreign Trade Control Law of Japan, the prior authorization by Japanese government should be required for export of those products from Japan.

#### F9704